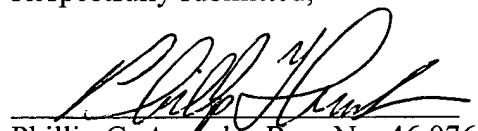


REMARKS

Claims 2-4 are cancelled. Claims 5-32 have been added. Please enter the Preliminary Amendment prior to calculating the filing fee. Examination of the amended application is respectfully requested.

Respectfully submitted,

  
Phillip G. Avruch - Reg. No. 46,076  
RABIN & BERDO, P.C.  
Telephone: 202-659-1915  
Telefax: 202-659-1898  
CUSTOMER NO. 23995

December 26, 2001  
Date

SMR:tlc

**MARKED VERSION OF AMENDED CLAIM**

1. (Amended) A method of forming a resist pattern on a semiconductor substrate, comprising [the steps of]:
  - forming a resist film on the semiconductor substrate;
  - supplying a developing solution [onto] on the resist film to remove the resist film, wherein a portion of the resist film remains on the semiconductor substrate; and
  - [submerging the substrate and the resist film formed thereon in a rinsing liquid kept in a rinsing tank; and
  - applying ultrasonic vibration to the rinsing liquid to rinse the developing solution from the resist film submerged in the rinsing liquid]
  - rinsing the developing solution from the portion of the resist film by a rinsing liquid to which ultrasonic vibration is applied.